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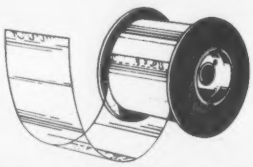

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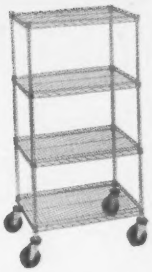

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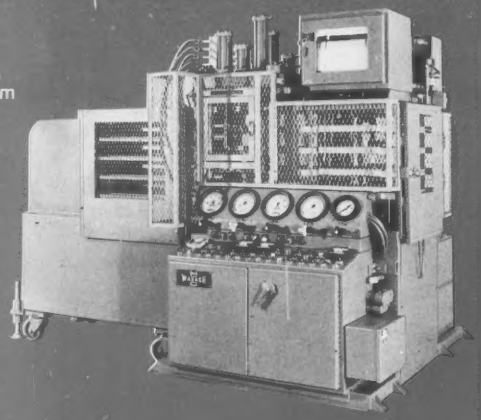

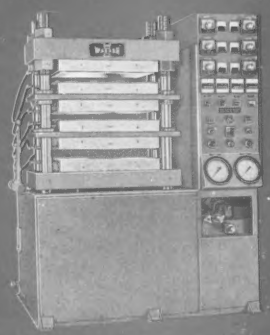

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Official Show Issue

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COMING IN FEBRUARY:

The use of digital/analog devices—A/D, D/A, filters, codecs, analog microprocessors, read/write chips, etc., is expected to grow rapidly in the near future. That's why EPP editors feel the time is ripe for a detailed examination of what's new in these items and to review new developments in incoming inspection of them. You'll read all about it in February EPP, the issue in which you'll also find a detailed feature updating the latest trends in computer-aided design and manufacturing; hybrid microelectronics; connectors and interconnections, and wire and cable. Keep your eye peeled for February EPP!

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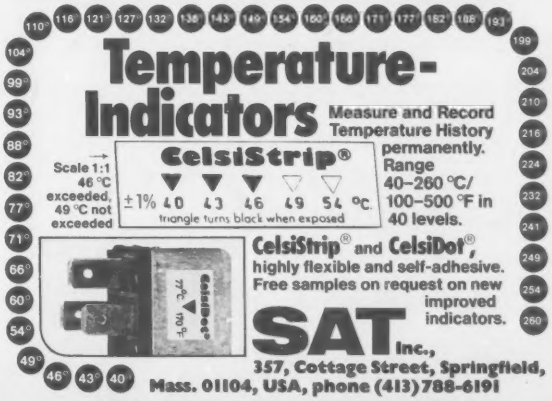
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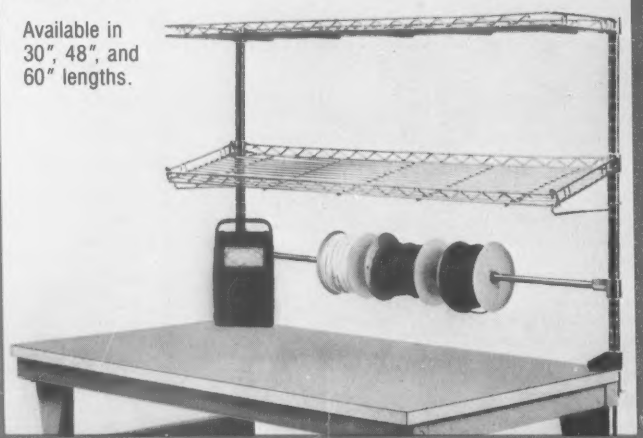

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